

- **Bill of Materials**
  - Assembly name and revision
  - PCB part number and PCB revision
  - Reference designators with corresponding quantities
  - Part numbers (those used in your system)
  - Manufacturers and manufacturer part numbers
  - Component descriptions
  - If firmware is required, please list each firmware as a BoM line item (include revision)
  - Indicate approved alternate components
- **CAD (ASCII data)**
  - This data is needed to perform a design for manufacturing (DFM) analysis
  - Acceptable formats include: .pcb, .min, .asc or ODB++
- **PCB Gerber files**
  - Please include outside board dimensions and PCB fab specs
  - RS-274X extended Gerber format preferred, Rs-274D acceptable
- **Requirements**
  - IPC Class 2 or Class 3?
  - Solder type: Leaded or Lead-free?
  - Flux type preference: Water soluble or no-clean?
  - Compliance: RoHS or Non-RoHS?
  - Special instructions/processes:
    - Pre-bake
    - Conformal coat
    - Lot traceability
    - Potting
    - Other
- **Testing (if applicable)**
  - Test/burn-in requirements (include procedures)
  - Describe test equipment required
  - Schematic(s) (PDF preferred)
- **Box Build (if applicable)**
  - Mechanical assembly drawings and specifications (PDF preferred, Solid Works acceptable)
- **Not Required, But Preferred:**
  - Assembly drawings for SMT component locations/orientation